

UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO. : 6,835,634 B1
DATED : December 28, 2004
INVENTOR(S) : Fazan et al.

Page 1 of 1

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Title page,

Item [56], **References Cited, OTHER PUBLICATIONS**,
“Van Zant,” reference, replace “Microchipn” with -- Microchip --.

Column 1,

Line 52, after “reducing” delete “,”.

Column 3,

Line 54, replace “crow” with -- grow --.

Column 4,

Line 40, after “(solid)+” replace “O₂” with -- 3O₂ --.

Column 5,

Line 21, after “claim 1” insert -- , --.

Lines 21-22, delete “comprises substantially only” and insert -- consists essentially of --.

Line 23, delete “further comprising” and insert -- wherein forming the field isolation region comprises --.

Line 24, delete “wafer” and insert -- substrate --.

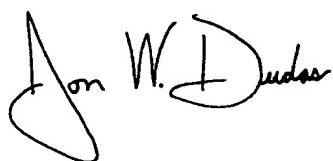
Line 26, delete “claim 1, further comprising” and insert -- claims 3, wherein forming the field isolation region comprises --.

Line 27, delete “semiconducting wafer” and insert -- semiconductor substrate --.

Line 38, delete “200° C.” and insert -- 900° C. --.

Signed and Sealed this

Twenty-eighth Day of February, 2006



JON W. DUDAS
Director of the United States Patent and Trademark Office